Phase Isolated Simultaneous V & I DAQ Reference Design Optimized for Size, Performance, and Cost

Designed for:
Public Release

Assembly Variant:
001

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Revision History

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<th>Rev</th>
<th>EDN #</th>
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Variant/Label Table

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<tr>
<th>Variant</th>
<th>Label Text</th>
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<tr>
<td>001</td>
<td>ChangeMe!</td>
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<tr>
<td>002</td>
<td>ChangeMe!</td>
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PCB Label

Size: 0.65" x 0.20"

Variant/Application Notes:

ZZ1

Variant/Assembly Notes:

- ESD sensitive, ESD precautions shall be observed.
- These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Contact: http://www.ti.com/support

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PCB Number: TIDA-01472
PCB Rev: E1

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PCB Logo

Pb-Free Symbol

FCC disclaimer

+/-300V

Pb-Free Symbol

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